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Application Number	10/687,519
Filing Date	October 16, 2003
First Named Inventor	Van Nguyen Truskett
Art Unit	1762
Examiner Name	Unassigned
Attorney Docket Number	P75/MII-35-17-03

Total Number of Pages in This Submission

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Signature	
Date	February 26, 2004

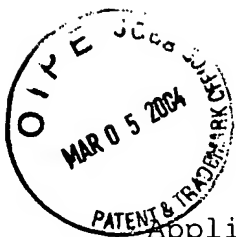
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IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Applicant: Truskett et al.

PATENT APPLICATION

Serial No.: 10/687,519

Group Art Unit: 1762

Filing Date: October 16, 2003

Examiner: Unassigned

For: LOW SURFACE ENERGY TEMPLATES

INFORMATION DISCLOSURE STATEMENT

Commissioner
for Patents
Alexandria, VA 22313-1450

Sir:

The following information is submitted in compliance with Applicants' duty of disclosure under 37 C.F.R. § 1.56. Form PTO-1449 and a copy of each reference recited below accompanies this document. It is respectfully requested that the cited information be expressly considered during the prosecution of this application, and the references be made of record therein and appear among the "references cited" on any patent to issue therefrom.

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5

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Application Number

10/687.519

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First Named Inventor

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Group Art Unit

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Examiner Name

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U.S. PATENT DOCUMENTS

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